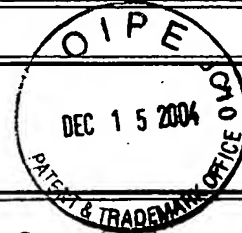


## SUPPLEMENTAL APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

**Title of  
Invention**

High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascene Interconnect Process

Application Type: regular, utility

Attorney Docket Number: 1875.0230001/JDE

Correspondence address:

**Customer Number:**

26111

\*26111\*

Continuing Data:

This is a Continuation of US application number 09/753,664, filed 2001-01-04.

Inventor Information:

Inventor 1:

**Applicant Authority Type:** Inventor  
**Citizenship:** CN  
**Given Name:** Liming  
**Family Name:** Tsau  
**City of Residence:** Irvine  
**State of Residence:** CA  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 14591 Fir Avenue  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Irvine  
**State of Mailing Address:** CA  
**Postal Code of Mailing Address:** 92606  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:**

## Attorney Information:

**Name****Registration Number**

Jason D. Eisenberg

~~43,477~~ 43,447